



EMSOFT 2018



"view of the city of Turin" (http://www.dianliwenmi.com/posting_3861909.html)

Call for Papers International Conference on Embedded Software September 30 – October 5, 2018 Torino, Italy

The ACM SIGBED International Conference on Embedded Software (EMSOFT) brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

Submissions are invited on all aspects of embedded software systems. These include, but are not limited to:

- Embedded software design and analysis
- Formal modeling and verification
- Testing, validation, and certification
- Model- and component-based approaches
- Operating systems and middleware for embedded systems
- Embedded software for distributed, networked systems
- Embedded software deployment on multi- and many-core processors
- Safety-critical and mixed-critical embedded software design
- Time-critical embedded systems
- Scheduling and execution time analysis
- QoS management and performance analysis
- Energy-efficient embedded software
- Embedded software security
- Embedded software architectures for intensive data- and signal processing
- Software design for cyber-physical systems
- Robust implementation of control systems
- Empirical studies and their reproduction, and confirmation

- Application areas, e.g. , automotive, avionics, energy, health care, mobile devices, multimedia, machine learning, and autonomous systems

A Special IoT (Internet of Things) Day will be organized jointly by all conferences in ESWEEK. Papers on IoT with the distinctive EMSOFT angle are very welcome and should be submitted to EMSOFT.

Papers should represent original work, not formerly published or submitted for publication in other forums. A blind review process will be enforced. Authors should not reveal authorship directly or indirectly through references.

EMSOFT will follow a two-stage review process, where papers passing the first stage of reviews will be asked to revise their work based on reviewer comments within a short time frame of around two weeks. Accepted papers will participate in the direct journal publication track and appear in IEEE TCAD (see below). Formal proceedings will still be published by ACM and IEEE.

Further information and formatting instructions is available on the site <http://www.esweek.org/>

Abstract Submission:

March 27, 2018

Full Paper Submission:

April 3, 2018 (firm deadline)

Conference:

Sep. 30 – Oct. 5, 2018

Venue:

Torino Incontra, Torino, Italy

Journal-integrated Publication Model: ESWEEK 2018 features a journal-integrated publication model where accepted papers will be published in the IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD).

ESWeek General Chairs:

Soonhoi Ha, Seoul National University, South Korea
Petru Eles, Linköping University, Sweden

EMSOFT Program Chairs:

Björn Brandenburg, MPI-SWS, Germany
Sriram Sankaranarayanan, U. of Colorado Boulder, USA